

ABSTRACT

**SEMICONDUCTOR DEVICE, SUBSTRATE FOR A SEMICONDUCTOR DEVICE,
METHOD OF MANUFACTURE THEREOF, AND ELECTRONIC INSTRUMENT**

A semiconductor device comprising a substrate including a metal portion and a resin portion and having a plurality of through holes formed in the resin portion, conductive members formed within the through holes, a semiconductor chip attached to one surface of the substrate, and a plurality of solder balls attached to the other surface of the substrate. The semiconductor chip and solder balls are electrically connected through the conductive members.

FIG. 2B